Special Issue

Assembly System Design in the Industry 4.0

Message from the Guest Editors

Reviews, original models and quantitative methods, technologies, management techniques and disruptive approaches are welcomed as well as industrial case studies and experiences from the field. Relevant topics include, but are not limited to:

- Design and management of smart assembly systems
- Digital assembly and digital-twins
- Human-Machine interaction in assembly systems
- Machine learning and artificial intelligence techniques for assembly and manufacturing
- Self-adaptive and self-learning assembly systems;
- Intelligent support systems and augmented reality technologies for operator assistance
- Human factors in assembly systems 4.0
- Optimization and self-optimisation models for assembly line balancing and sequencing to quickly reconfigure the system
- Self-configuration and self-diagnosis methods based on Internet of Things technologies
- Novel industrial and real world case studies to test and spread the adoption of "Assembly System Design in the Industry 4.0"

Guest Editors

Prof. Dr. Maurizio Faccio

Prof. Mauro Gamberi

Dr. Francesco Gabriele Galizia

Prof. Dr. Francesco Pilati

Deadline for manuscript submissions

closed (31 December 2021)

Applied Sciences

Applied Sciences

mdpi.com/journal/
applsci

About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized,
researchers may lose themselves in the deep forest of
the ever increasing number of subfields being created.
This open access journal *Applied Sciences* has been
started to link these subfields, so researchers can cut
through the forest and see the surrounding, or quite
distant fields and subfields to help develop his/her own
research even further with the aid of this multi-
dimensional network.

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32,
20133 Milano, Italy

Author Benefits

Open Access:
free for readers, with article processing charges (APC) paid
by authors or their institutions.

High Visibility:
indexed within Scopus, SCIE (Web of Science), Ei
Compendex, Inspec, CAPlus / SciFinder, and other
databases.

Journal Rank:
JCR - Q2 (Engineering, Multidisciplinary) / CiteScore - Q1
(General Engineering)

MDPI